

### REMARKS/ARGUMENTS

The applicant's attorneys appreciate the Examiner's thorough search and remarks.

Claims 1 and 11 have been rejected as anticipated by Potter et al., U.S. Patent No. 5,426,263. Reconsideration is requested.

Potter et al. show a device which includes a leadless component 10 disposed between two circuit boards 30, 32. The leadless component 10 shown by Potter et al. is a package which includes a semiconductor IC 20 disposed on a substrate 22 and encapsulated by an enclosure 24.

On the other hand, claims 1 and 11 call for a semiconductor die which is electrically and mechanically connected directly to conductive pads of a circuit board or a thermally conductive substrate. Specifically, claims 1 and 11 call for a layer of conductive adhesive to be interposed between the contacts of a semiconductor die and the conductive pads of a circuit board or a thermally conductive substrate. Potter et al. neither show nor suggest such a combination of elements. Reconsideration is requested.

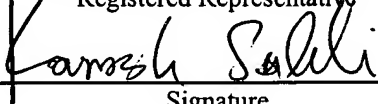
Each of the remaining claims is a dependent claim which depends from one of claims 1 and 11. Each dependent claim includes other limitations, which in combination with those of its base claim, are not shown or suggested by the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

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Kourosh Salehi

Name of applicant, assignee or  
Registered Representative



Signature

September 14, 2004

Date of Signature

Respectfully submitted,



Kourosh Salehi

Registration No.: 43,898

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

KS:gl